
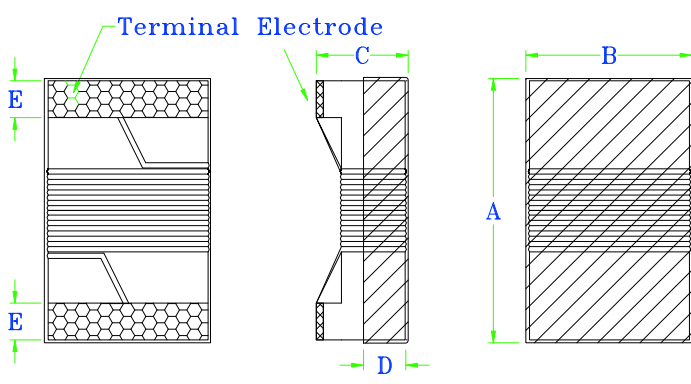


ECN HISTORY LIST

版別	ECN NO.	變更內容	變更日期	確認章
0		新版本	2018/1/17	

SPECIFICATION FOR APPROVAL

COMMODITY	HIGH FREQUENCY WOUND CHIP INDUCTOR	SPEC NO.	SP-0180117001
ITEM	JWI 0603F-R47J-I01 Green	版本：D	表單編號：QRRD-01-02

(1) DIMENSION: (UNIT: mm)		DIM.	TOL.
	A	1.80	Max
	B	1.20	Max
	C	1.20	Max
	D	0.38	Ref
	E	0.35	±0.1

(2) ELECTRICAL CHARACTERISTIC		TEST INSTRUMENTS.
INDUCTANCE	470 ± 5% nH	<input checked="" type="checkbox"/> AGILENT 4294A Precision Impedance Analyzer. <input type="checkbox"/> AGILENT 4285A Precision L.C.R. Meter. <input type="checkbox"/> HP-4286A RF L.C.R. Meter.
TEST FREQUENCY	100 MHz	<input type="checkbox"/> ZENTECH 3302 Automatic Components Analyzer. <input type="checkbox"/> ZENTECH 101 L.C.R. Meter.
Q	30 (min)	<input type="checkbox"/> WAYNE KERR 6420 Precision Impedance Analyzer. <input checked="" type="checkbox"/> ZENTECH 1320 BIAS CURRENT.
TEST FREQUENCY	100 MHz	<input checked="" type="checkbox"/> ZENTECH 502AC Resistance Merter.
SRF	700 (min) MHz	<input type="checkbox"/> ADEX AX-1155B DC Low Ohm Meter.
RDC	4.0 (max) Ω	
IDC	75 (max) mA	

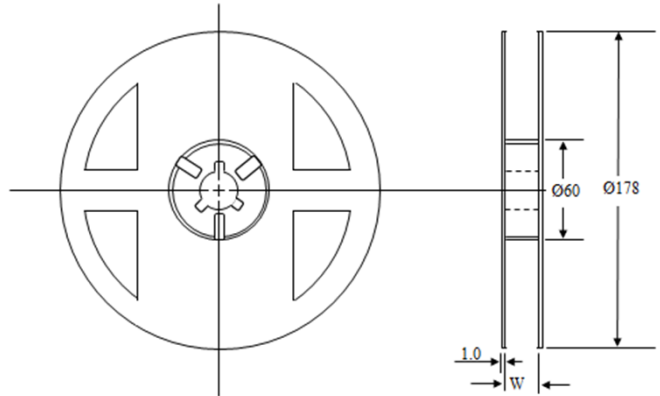
REMARK :

PURCHASER CONFIRMED	APPROVED	CHECKED	DRAWN
			

Packaging Information

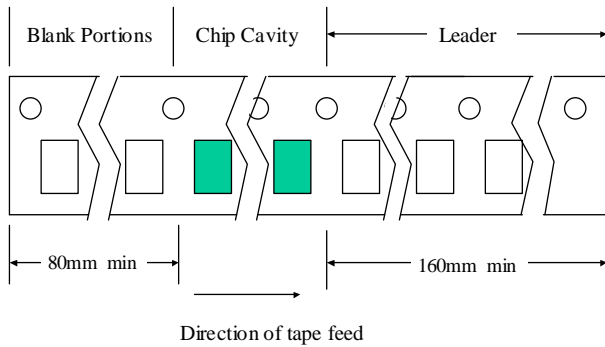
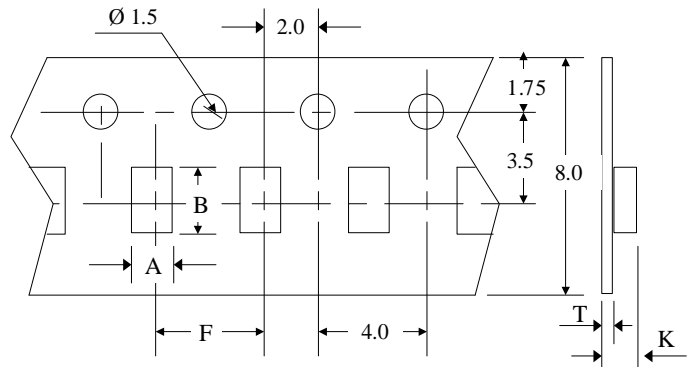
Packing Quantity

Size	Reel
JWI 0603F	3000



Dimensions (unit: m/m)

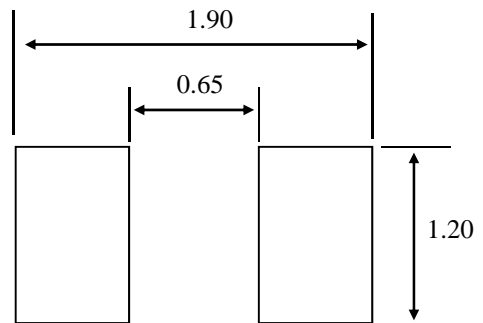
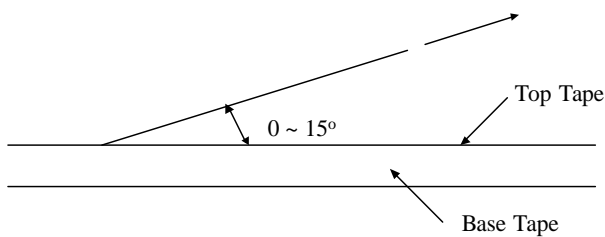
Chip Cavity		Insert Pitch F	Tape Thickness		
A	B		K	T	W
1.35	1.90	4.00	1.15	0.20	8.00



Recommended Pattern

Top Tape Strength

The top tape requires a peel-off force of 0.2 to 0.7N in the direction of the arrow as illustrated below.



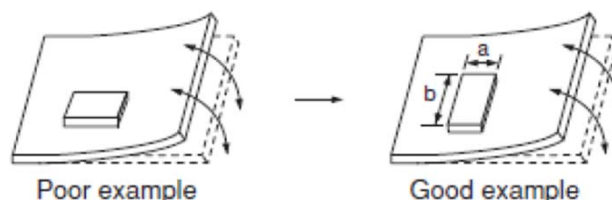
SAFETY NOTES & PRECAUTION

1. Products may not be used in applications that directly affect the personal safety or cause significant impacts and losses to society. If you apply to these applications, please be sure to contact us at first to confirm.
2. The Storage period is less than 12 months. Ensure to follow the Storage conditions (Temperature: 5 to 30°C, Humidity: 10 to 65% RH or none). If the Storage period is exceeded the limit. the electrodes might be deteriorate / oxidized and affect soldering. Solderability should be checked if this period is exceeded.

Other storage precaution:

- a) Products should be stored on the pallet for the prevention of the influence from humidity, dust and so on.
 - b) Products should be stored in the warehouse without heat shock, vibration, direct sunlight and so on.
 - c) Do not unpack the minimum package until immediately use. After unpacking, reseal promptly or store in desiccator with a desiccant.
 - d) Do not store product in bulk to prevent coils and [arts being damaged.
3. Do not use or store in locations where there are corrosive gases (salt, acid, alkali, etc.).
 4. soldering condition for mounting should be within the specification range.
If overheated, a short circuit, performance deterioration, or lifespan shortening may occur.
 5. When using, try to avoid excessive ,mechanical impact on the product such as collision/drop...etc.
 6. When assembling a printed circuit board with a new mounted chip, be careful to avoid assembly deformation of the circuit board that may cause the overall or partial distortion of the circuit board such as at screw tightening position.
 7. Self heating (temperature increase) occurs when the power is turned ON, so the tolerance should be sufficient for the thermal design.
 8. Do not expose the the products to magnets or magnetic fields.
 9. If you would like to use this products for more stringent safety or reliability of performance and/or quality requirements, or its failure, malfunction or trouble may cause serious damage to society, individuals or property, or you have special requirement beyond specification or condition in the catalogue, please contact us.
 10. PCB should be designed so that products are not subjected to the mechanical stress caused by warping of the board as shown below. Bending and twisting of PCB will cause excessive mechanical stress and lead to crack in the product as well.

Products should be located in the sideways



11. Cleaning brush shall not touch the winding portion of the product to prevent the breaking of wire.
Cleaning could cause failure and degradation of product.
12. Care should be taken when transporting or product to avoid excessive vibration or mechanical shock. Product could be famaged by external mechanical pressure, stacked under heavy object, as strong shaking and drop.